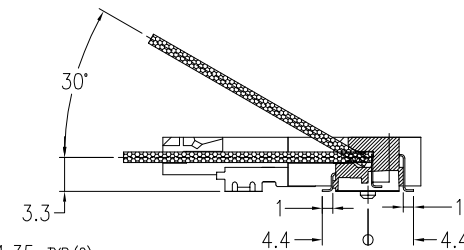
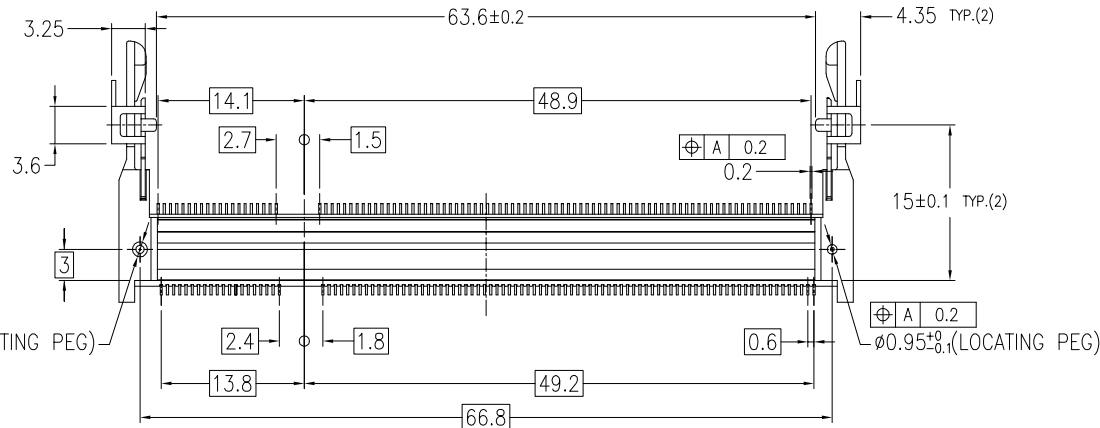
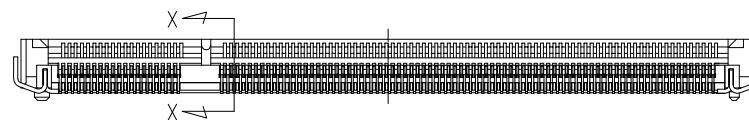
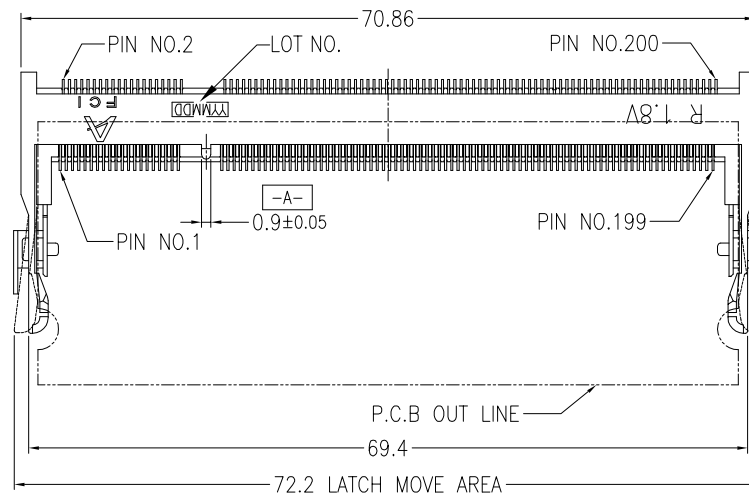
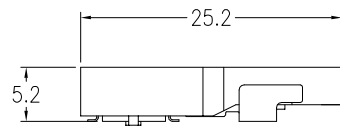


PRODUCT NO.
10033854-*52**



NOTE

1. PRODUCT SPEC. : GS-12-195
2. PACKAGING SPEC. : GS-14-786
3. MATERIAL
 - 1) HOUSING : LCP, UL94V-0, COLOR BLACK
 - 2) CONTACT : COPPER ALLOY
 - 3) HOLD DOWN : BRASS
4. FINISH
 - 1) TERMINAL : SEE TABLE
 - 2) HOLD DOWN : SEE TABLE
5. CO-PLANARITY : 0.1 MAX.(INCLUDE HOLD DOWN)
6. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.
7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260° PEAK TEMPERATURE FOR 10 SECONDS IN A REFLOW SOLDER APPLICATION.

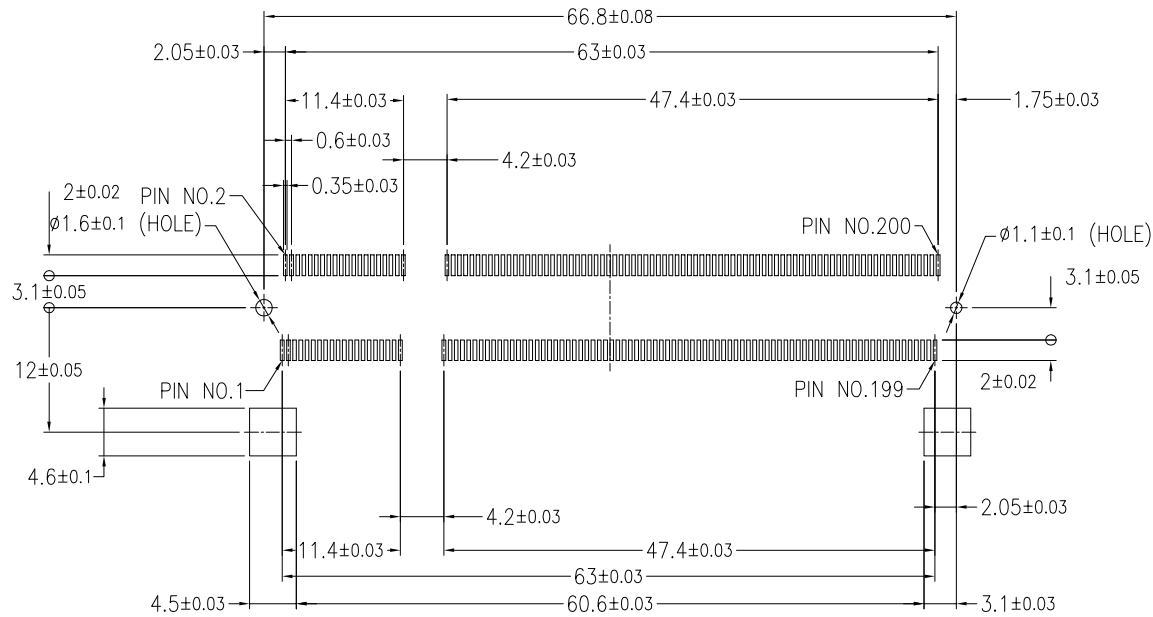
⌀1.45^{+0.1}₀(LOCATING PEG)

⌀0.95^{+0.1}₀(LOCATING PEG)

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY	FCI	www.fciconnect.com
ltr	ecn no	dr	date					
2		M H	8/28/'03	linear	.X ± 0.20	projection	title	DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y
3		M H	4/2/'04		.XX ± 0.10			
4		M H	6/29/'04	angles	0° ± 5°		product family 50UF SO-DIMM	code JP
A	J04-0401	M H	9/28/'04	dr	M.Hasegawa	6/29/'04		
B	T05-0022	R C	11/9/'04	enr	M.Hasegawa	6/29/'04	size	dwg no
C	T05-0229	R C	10/12/'05	chr			scale	
D	pg08-0333	B L	12/1/'08	appd			2:1	
sheet	revision	D	D	D	D			
index	sheet	1	2	3	4			



PRODUCT NO.
10033854-*52**

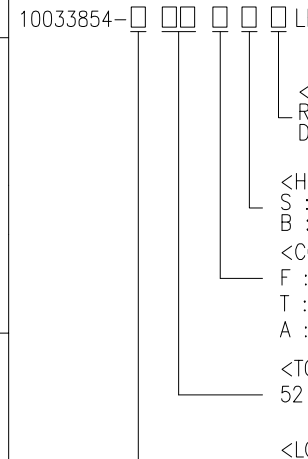


RECOMMENDED MOUNTING P.C.B LAYOUT

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		www.fciconnect.com			
ltr	ecn no	dr	date	linear	.X ± 0.20	projection		title DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y			
D					.XX ± 0.10						
				angles	0° ± 5°			product family 50UF SO-DIMM size dwg no			
				dr	M.Hasegawa	6/29/04	MM				
				enr	M.Hasegawa	6/29/04	scale	B 10033854			
				chr			2:1				
				appd				code JP sheet 2 of			
sheet index	revision sheet										



PRODUCT NO.	LOCATING PEG	TERMINAL CONTACT AREA FINISH	HOLD DOWN FINISH	SOLDER TAIL FINISH
10033854-052FSLF	YES	Au FLASH	PURE Sn PLATING	Au FLASH
10033854-152FSLF	NO			
10033854-052TSLF	YES	Au 0.3um MIN.		
10033854-152TSLF	NO			
10033854-052ASLF	YES	Au 0.76um MIN.		
10033854-152ASLF	NO			
10033854-052FB	YES	Au FLASH	Sn-Pb PLATING	
10033854-152FB	NO			
10033854-052TB	YES	Au 0.3um MIN.		
10033854-152TB	NO			
10033854-052AB	YES	Au 0.76um MIN.		
10033853-152AB	NO			
10033854-252FSLF	YES	Au FLASH	PURE Sn PLATING	Pure Sn PLATING
10033854-352FSLF	NO			
10033854-252TSLF	YES	Au 0.3um MIN.		
10033854-352TSLF	NO			
10033854-252ASLF	YES	Au 0.76um MIN.		
10033854-352ASLF	NO			
10033854-252FB	YES	Au FLASH	Sn-Pb PLATING	
10033854-352FB	NO			
10033854-252TB	YES	Au 0.3um MIN.		
10033854-352TB	NO			
10033854-252AB	YES	Au 0.76um MIN.		
10033854-352AB	NO			
10033854-452FS	YES	Au FLASH	PURE Sn PLATING	Sn-Pb PLATING
10033854-552FS	NO			
10033854-452TS	YES	Au 0.3um MIN.		
10033854-552TS	NO			
10033854-452AS	YES	Au 0.76um MIN.		
10033854-552AS	NO			
10033854-452FB	YES	Au FLASH	Sn-Pb PLATING	
10033854-552FB	NO			
10033854-452TB	YES	Au 0.3um MIN.		
10033854-552TB	NO			
10033854-452AB	YES	Au 0.76um MIN.		
10033854-552AB	NO			



<PACKING METHOD>
R : TAPE REEL
DEFAULT : TRAY

<HOLD DOWN FINISH>
S : Pure Sn
B : Sn-Pb
<CONTACT AREA FINISH>
F : Au FLASH
T : Au 0.3um MIN.
A : Au 0.76um MIN.

<TOTAL HEIGHT>
52 : 5.2mm

<LOCATING PEG, SOLDER TAIL FINISH>
0 : YES, Au FLASH
1 : NO, Au FLASH
2 : YES, Pure Sn PLATING
3 : NO, Pure Sn PLATING
4 : YES, Sn-Pb PLATING
5 : NO, Sn-Pb PLATING

For Rohs OPTIONS:
TAIL PLATING CODE MUST BE 0~3.
HOLD DOWN PLATING CODE MUST BE "S".
"LF" CODE IS EXIST IN THE END.
EX: 10033854-252TSLF

FOR NOT Rohs COMPATIBLE:
THIS "LF" CODE IS "BLANK".
EX:10033854-452TS

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		www.fciconnect.com							
ltr	ecn no	dr	date	linear	.X ± 0.20	projection		title DDR II 0.6 mm PITCH 200 POS. REVERSE TYPE ASS'Y							
D					.XX ± 0.10										
				angles	0° ±5°			product family 50UF SO-DIMM code JP							
				dr	M.Hasegawa 6/29/04										
				engr	M.Hasegawa 6/29/04			size dwg no							
				chr											
				appd				B 10033854							
sheet index	revision sheet														